



High power cycling capability
Low on-state and switching losses
Designed for traction and industrial applications

Phase Control Thyristor Type T243-500-28

Mean on-state current	I _{TAV}	500 A			
Repetitive peak off-state voltage	V _{DRM}	2000 ÷ 2800 V			
Repetitive peak reverse voltage	V _{RRM}				
Turn-off time	t _q	250, 320, 400, 500 µs			
V _{DRM} , V _{RRM} , V	2000	2200	2400	2600	2800
Voltage code	20	22	24	26	28
T _j , °C			-60 ÷ 125		

MAXIMUM ALLOWABLE RATINGS

Symbols and parameters		Units	Values	Test conditions	
ON-STATE					
I _{TAV}	Mean on-state current	A	500 614	T _c =95 °C, Double side cooled T _c =85 °C, Double side cooled 180° half-sine wave; 50 Hz	
I _{TRMS}	RMS on-state current	A	785	T _c =95 °C, Double side cooled 180° half-sine wave; 50 Hz	
I _{TSM}	Surge on-state current	kA	10.5 12.0	T _j =T _j max T _j =25 °C	180° half-sine wave; t _p =10 ms; single pulse; V _D =V _R =0 V; Gate pulse: I _G =2 A; t _{GP} =50 µs; di _G /dt≥1 A/µs
			11.0 12.5	T _j =T _j max T _j =25 °C	180° half-sine wave; t _p =8.3 ms; single pulse; V _D =V _R =0 V; Gate pulse: I _G =2 A; t _{GP} =50 µs; di _G /dt≥1 A/µs
I ² t	Safety factor	A ² ·10 ³	550 720	T _j =T _j max T _j =25 °C	180° half-sine wave; t _p =10 ms; single pulse; V _D =V _R =0 V; Gate pulse: I _G =2 A; t _{GP} =50 µs; di _G /dt≥1 A/µs
			500 640	T _j =T _j max T _j =25 °C	180° half-sine wave; t _p =8.3 ms; single pulse; V _D =V _R =0 V; Gate pulse: I _G =2 A; t _{GP} =50 µs; di _G /dt≥1 A/µs
BLOCKING					
V _{DRM} , V _{RRM}	Repetitive peak off-state and Repetitive peak reverse voltages	V	2000÷2800	T _{j min} < T _j <T _j max; 180° half-sine wave; 50 Hz; Gate open	
V _{DSM} , V _{RSM}	Non-repetitive peak off-state and Non-repetitive peak reverse voltages	V	2100÷2900	T _{j min} < T _j <T _j max; 180° half-sine wave; single pulse; Gate open	
V _D , V _R	Direct off-state and Direct reverse voltages	V	0.6V _{DRM} 0.6V _{RRM}	T _j =T _j max; Gate open	

TRIGGERING				
I_{FGM}	Peak forward gate current	A	8	$T_j=T_{j \max}$
V_{RGM}	Peak reverse gate voltage	V	5	
P_G	Gate power dissipation	W	4	$T_j=T_{j \max}$ for DC gate current
SWITCHING				
$(di_T/dt)_{crit}$	Critical rate of rise of on-state current non-repetitive ($f=1$ Hz)	A/ μ s	1600	$T_j=T_{j \max}$; $V_D=0.67V_{DRM}$; $I_{TM}=2100$ A; Gate pulse: $I_G=2$ A; $t_{GP}=50$ μ s; $di_G/dt \geq 2$ A/ μ s
THERMAL				
T_{stg}	Storage temperature	°C	-60÷50	
T_j	Operating junction temperature	°C	-60÷125	
MECHANICAL				
F	Mounting force	kN	14.0÷16.0	
a	Acceleration	m/s ²	50	Device clamped

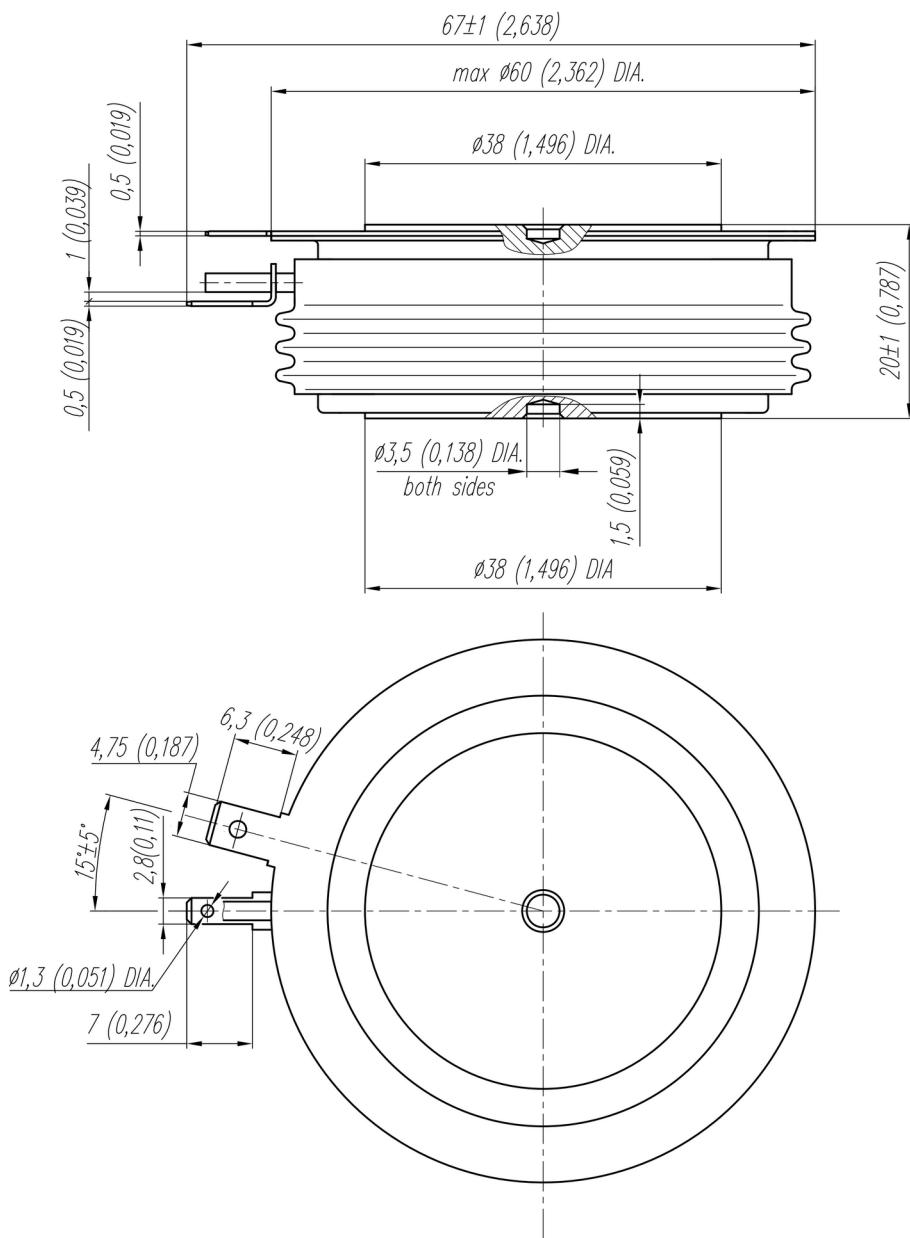
CHARACTERISTICS

Symbols and parameters		Units	Values	Conditions
ON-STATE				
V_{TM}	Peak on-state voltage, max	V	1.90	$T_j=25$ °C; $I_{TM}=1570$ A
$V_{T(TO)}$	On-state threshold voltage, max	V	1.027	$T_j=T_{j \max}$;
r_T	On-state slope resistance, max	$m\Omega$	0.671	$0.5 \pi I_{TAV} < I_T < 1.5 \pi I_{TAV}$
I_L	Latching current, max	mA	1000	$T_j=25$ °C; $V_D=12$ V; Gate pulse: $I_G=2$ A; $t_{GP}=50$ μ s; $di_G/dt \geq 1$ A/ μ s
I_H	Holding current, max	mA	300	$T_j=25$ °C; $V_D=12$ V; Gate open
BLOCKING				
I_{DRM}, I_{RRM}	Repetitive peak off-state and Repetitive peak reverse currents, max	mA	100	$T_j=T_{j \max}$; $V_D=V_{DRM}$; $V_R=V_{RRM}$
$(dv_D/dt)_{crit}$	Critical rate of rise of off-state voltage ¹⁾ , min	V/ μ s	200, 320, 500, 1000, 1600, 2000, 2500	$T_j=T_{j \max}$; $V_D=0.67V_{DRM}$; Gate open
TRIGGERING				
V_{GT}	Gate trigger direct voltage, max	V	3.00 2.50 1.50	$T_j=T_{j \min}$ $T_j=25$ °C $T_j=T_{j \max}$
I_{GT}	Gate trigger direct current, max	mA	400 250 150	$T_j=T_{j \min}$ $T_j=25$ °C $T_j=T_{j \max}$
V_{GD}	Gate non-trigger direct voltage, min	V	0.55	$T_j=T_{j \max}$;
I_{GD}	Gate non-trigger direct current, min	mA	60.00	$V_D=0.67V_{DRM}$; Direct gate current
SWITCHING				
t_{gd}	Delay time, max	μ s	0.55	$T_j=25$ °C; $V_D=1500$ V; $I_{TM}=I_{TAV}$; $di/dt=200$ A/ μ s;
t_{gt}	Turn-on time, max	μ s	5.00	Gate pulse: $I_G=2$ A; $V_G=20$ V; $t_{GP}=50$ μ s; $di_G/dt=2$ A/ μ s
t_q	Turn-off time ²⁾ , max	μ s	250, 320, 400, 500	$dv_D/dt=50$ V/ μ s; $T_j=T_{j \max}$; $I_{TM}=I_{TAV}$; $di_R/dt=-10$ A/ μ s; $V_R=100$ V; $V_D=0.67V_{DRM}$
Q_{rr}	Total recovered charge, max	μ C	2220	$T_j=T_{j \max}$; $I_{TM}=500$ A;
t_{rr}	Reverse recovery time, max	μ s	30	$di_R/dt=-10$ A/ μ s;
I_{rrM}	Peak reverse recovery current, max	A	148	$V_R=100$ V

THERMAL						
R_{thjc}	Thermal resistance, junction to case, max			0.0320	Direct current	Double side cooled
R_{thjc-A}				0.0704		Anode side cooled
R_{thjc-K}				0.0576		Cathode side cooled
R_{thck}	Thermal resistance, case to heatsink, max		°C/W	0.0060	Direct current	

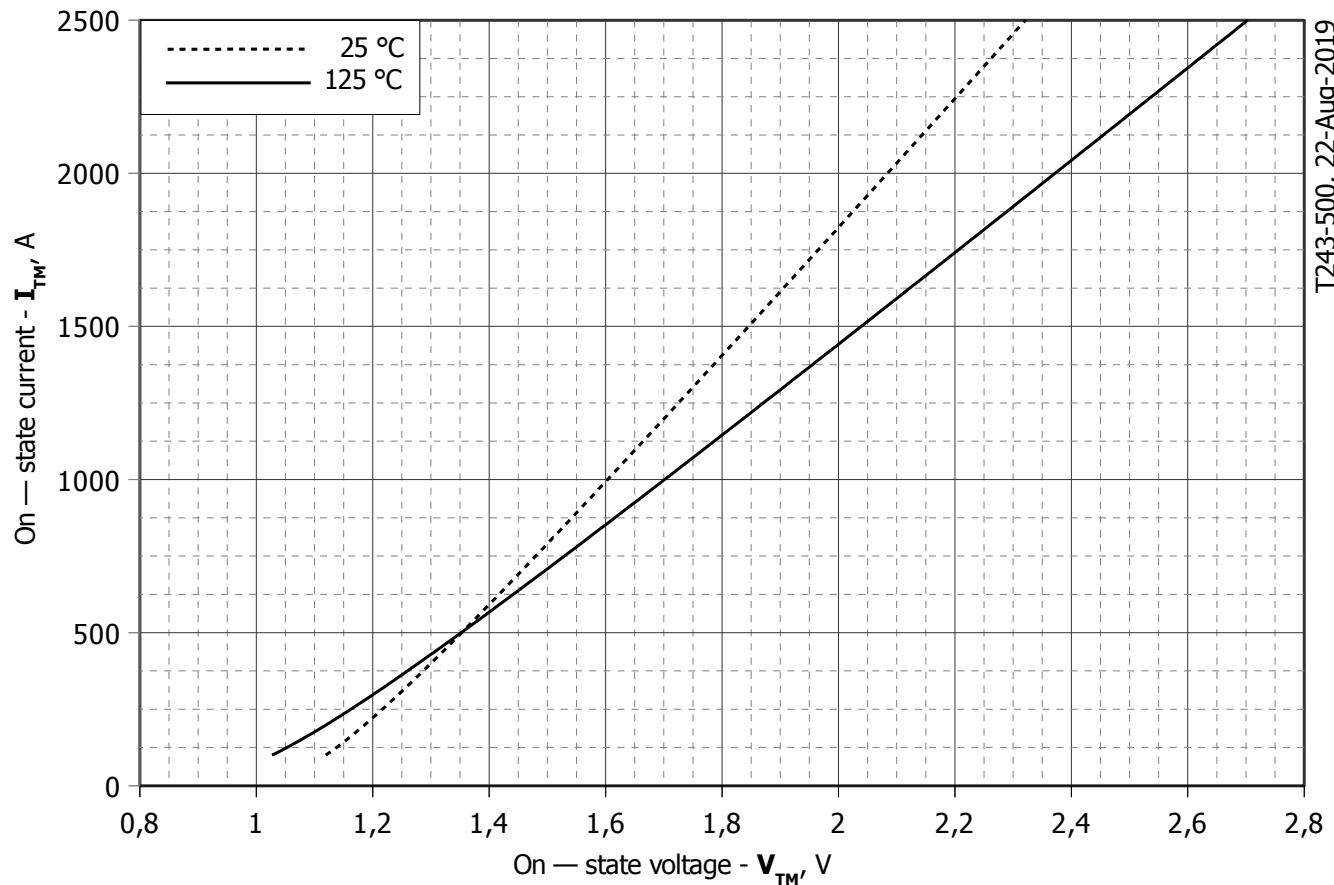
MECHANICAL						
W	Weight, max			g	260	
D_s	Surface creepage distance			mm (inch)	19.44 (0.765)	
D_a	Air strike distance			mm (inch)	12.10 (0.476)	

PART NUMBERING GUIDE							NOTES																							
T	243	500	28	A2	E2	N																								
1	2	3	4	5	6	7																								
1. Phase Control Thyristor							¹⁾ Critical rate of rise of off-state voltage																							
2. Design version							<table border="1"> <thead> <tr> <th>Symbol of Group</th><th>P2</th><th>K2</th><th>E2</th><th>A2</th><th>T1</th><th>P1</th><th>M1</th></tr> </thead> <tbody> <tr> <td>$(dv_0/dt)_{crit}, V/\mu s$</td><td>200</td><td>320</td><td>500</td><td>1000</td><td>1600</td><td>2000</td><td>2500</td></tr> </tbody> </table>								Symbol of Group	P2	K2	E2	A2	T1	P1	M1	$(dv_0/dt)_{crit}, V/\mu s$	200	320	500	1000	1600	2000	2500
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5. Critical rate of rise of off-state voltage, $V/\mu s$																														
6. Turn-off time ($dv_D/dt=50 V/\mu s$)																														
7. Ambient conditions: N – normal; T – tropical																														

OVERALL DIMENSIONS**Package type: T.C2**

All dimensions in millimeters (inches)

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**Fig 1 – On-state characteristics of Limit device**

Analytical function for On-state characteristic:

$$V_T = A + B \cdot i_T + C \cdot \ln(i_T + 1) + D \cdot \sqrt{i_T}$$

	Coefficients for max curves	
	$T_j = 25^\circ\text{C}$	$T_j = T_{j,\max}$
A	0.92140000	0.75180000
B	0.00046445	0.00064940
C	0.03399400	0.04745500
D	-0.00054491	-0.00087507

On-state characteristic model (see Fig. 1)

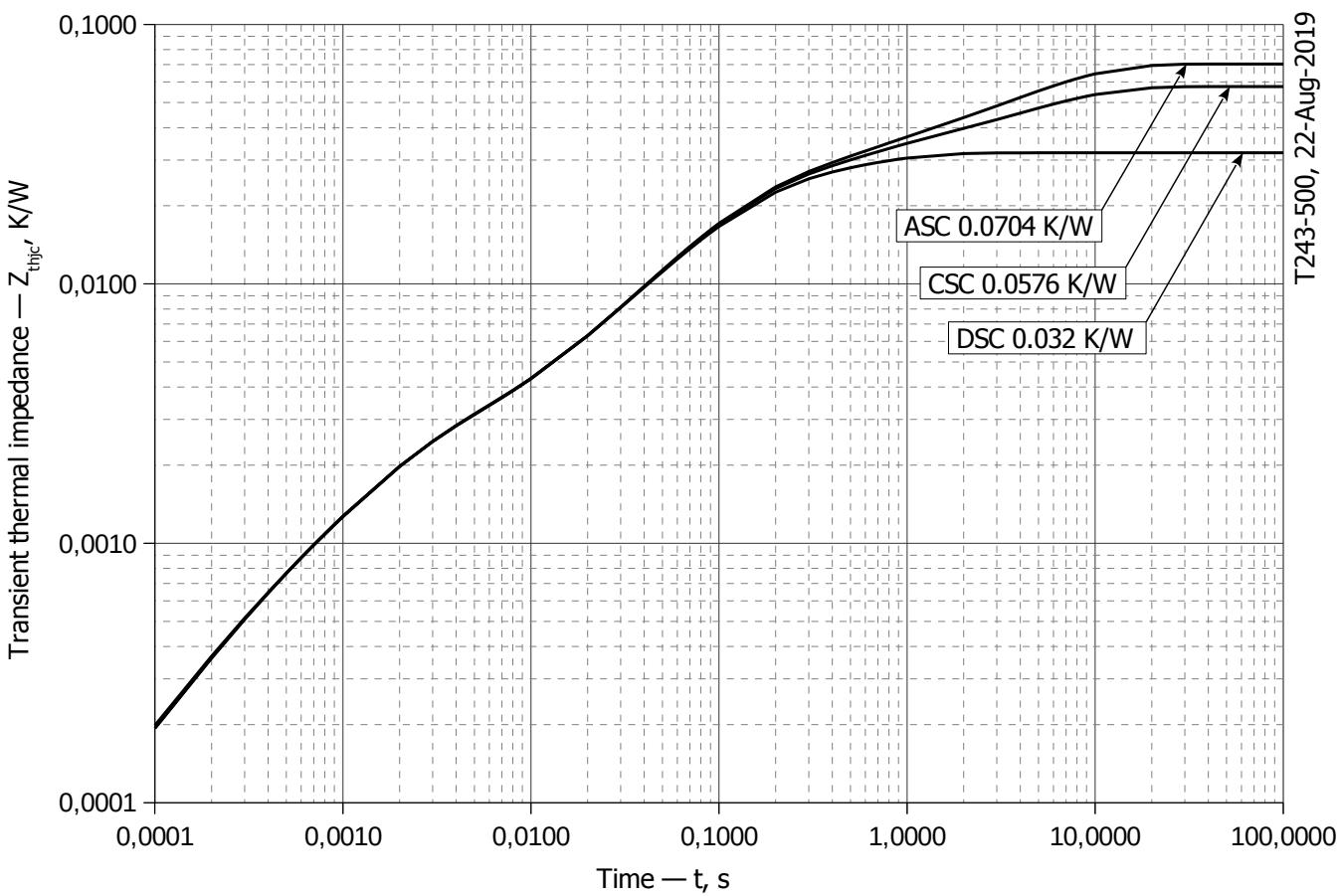


Fig 2 – Transient thermal impedance Z_{thjc} vs. time t

Analytical function for Transient thermal impedance junction to case Z_{thjc} for DC:

$$Z_{thjc} = \sum_{i=1}^n R_i \left(1 - e^{-\frac{t}{\tau_i}} \right)$$

Where $i = 1$ to n , n is the number of terms in the series.

t = Duration of heating pulse in seconds.

Z_{thjc} = Thermal resistance at time t .

R_i = Amplitude of p_{th} term.

τ_i = Time constant of r_{th} term.

DC Double side cooled

i	1	2	3	4	5	6
R_i , K/W	0.000005619	0.01031	0.01922	0.0004148	0.001895	0.0001521
τ_i , s	7.790	0.5094	0.09719	0.01725	0.0016	0.0002257

DC Anode side cooled

i	1	2	3	4	5	6
R_i , K/W	0.0381	0.008681	0.01867	0.001961	0.0001787	0.002771
τ_i , s	5.351	0.4584	0.09325	0.001734	0.0002174	0.9059

DC Cathode side cooled

i	1	2	3	4	5	6
R_i , K/W	0.02561	0.001472	0.01786	0.001926	0.0001928	0.01052
τ_i , s	5.328	0.1832	0.09031	0.001714	0.0002598	0.525

Transient thermal impedance junction to case Z_{thjc} model (see Fig. 2)

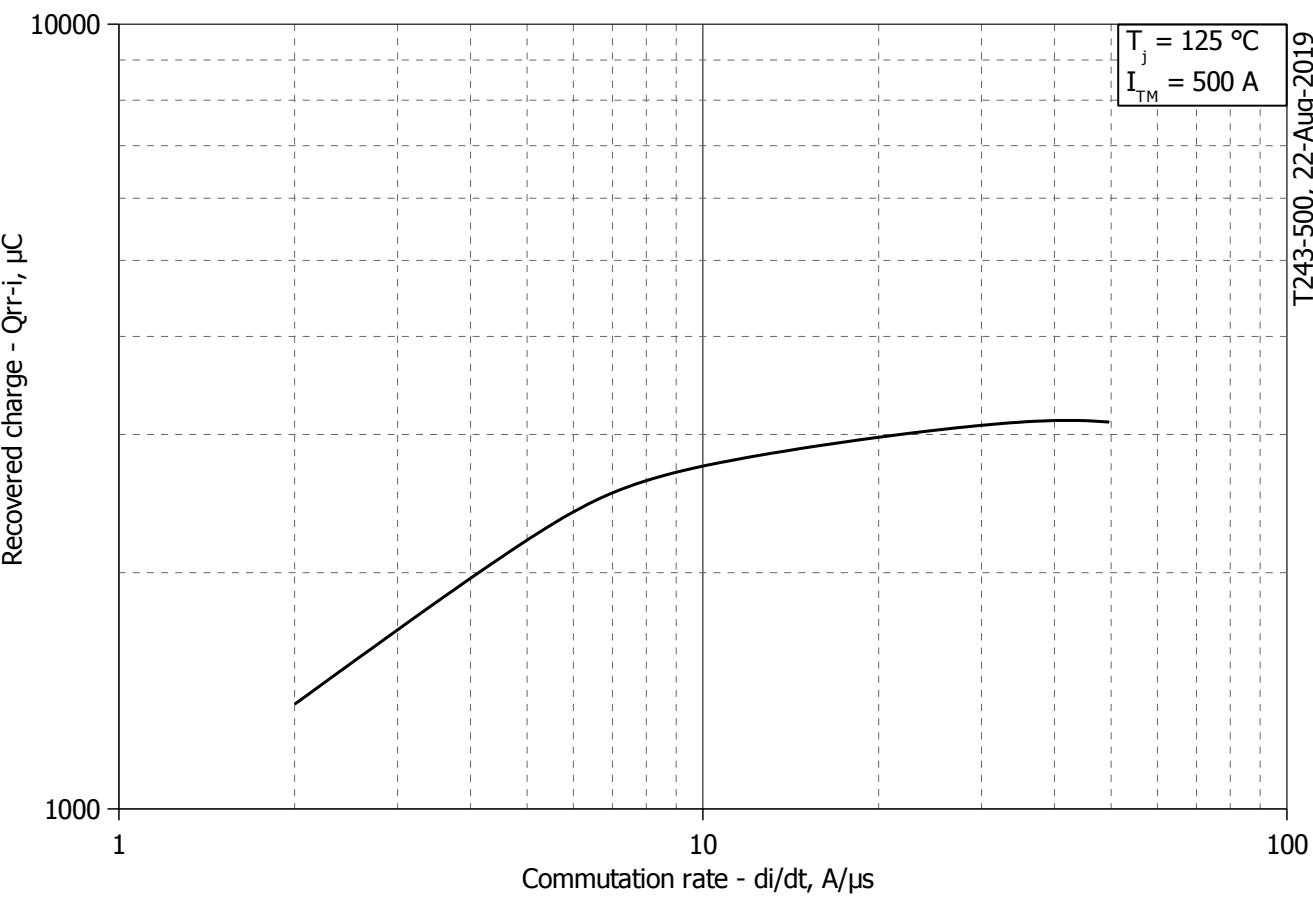


Fig 3 – Maximum recovered charge Q_{rr-i} (integral) vs. commutation rate di_R/dt

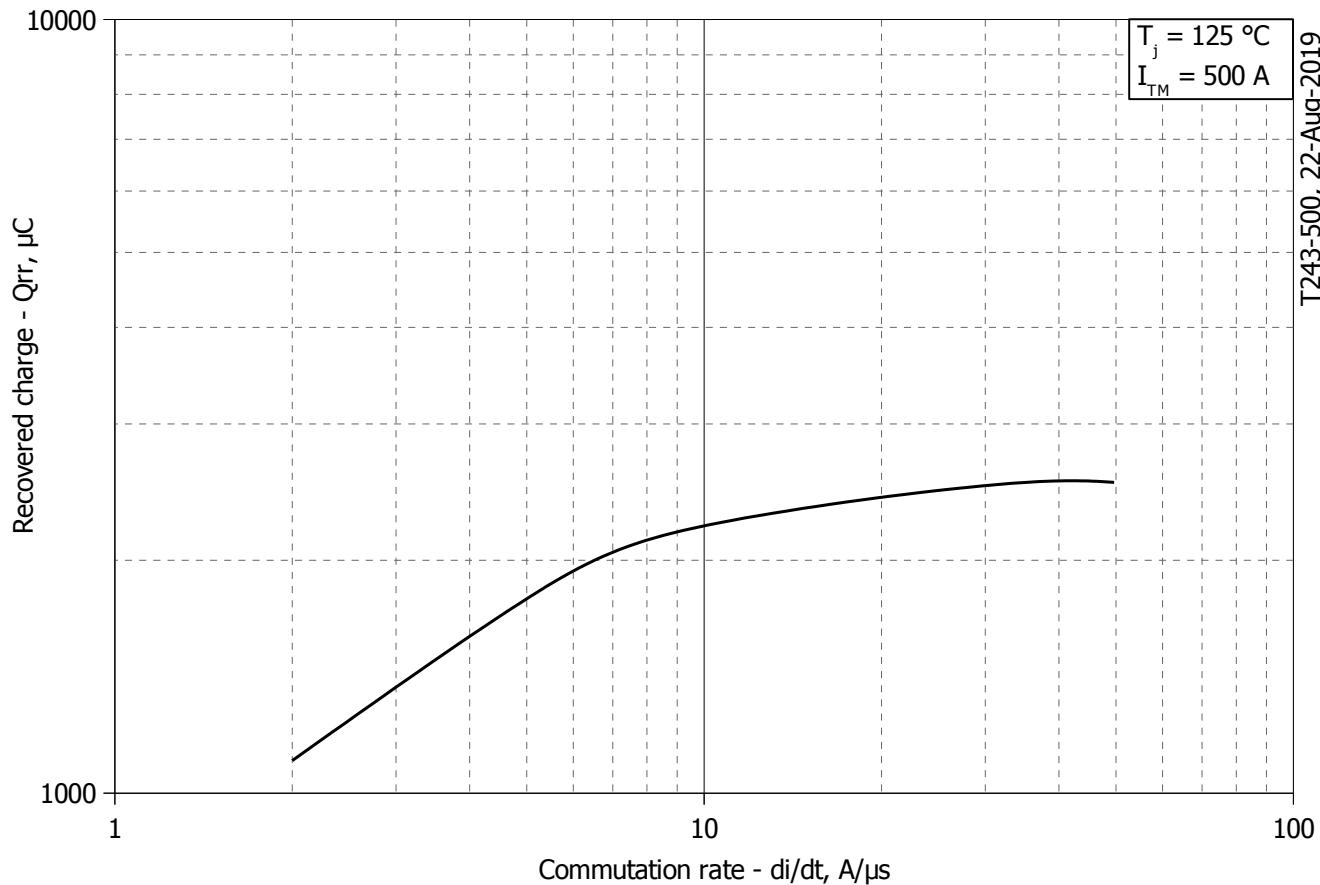
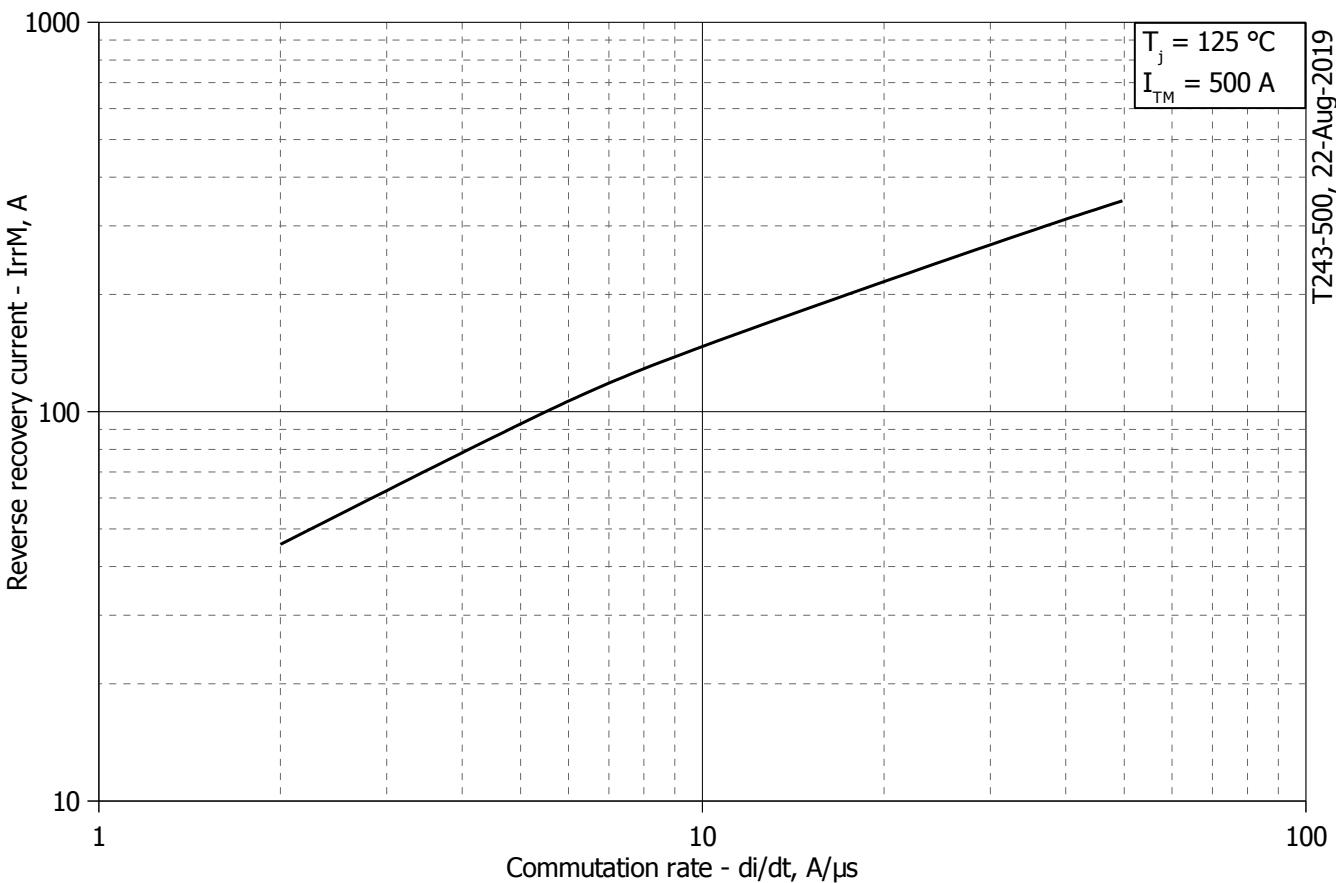
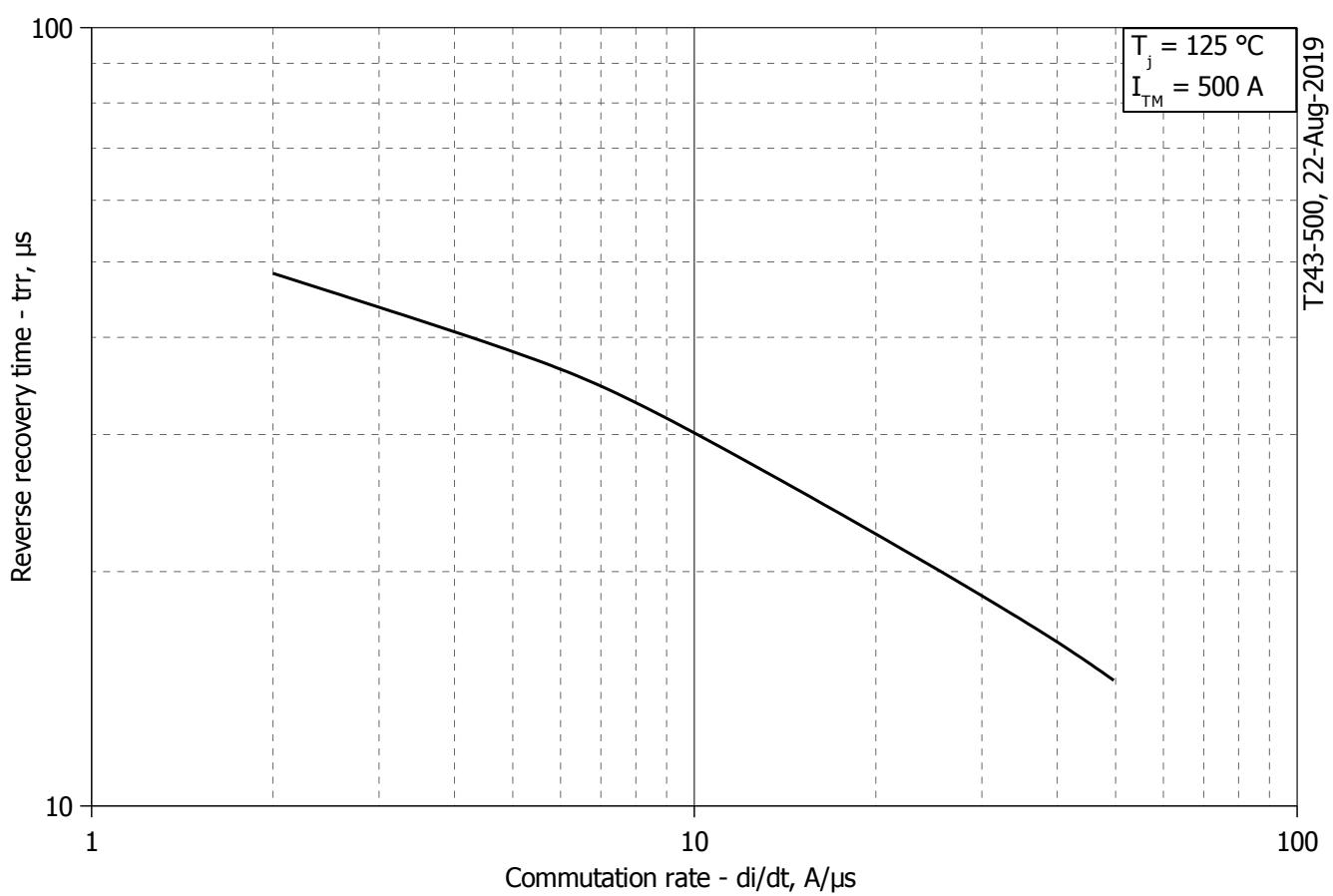


Fig 4 – Maximum recovered charge Q_{rr} vs. commutation rate di_R/dt (25% chord)



T243-500, 22-Aug-2019



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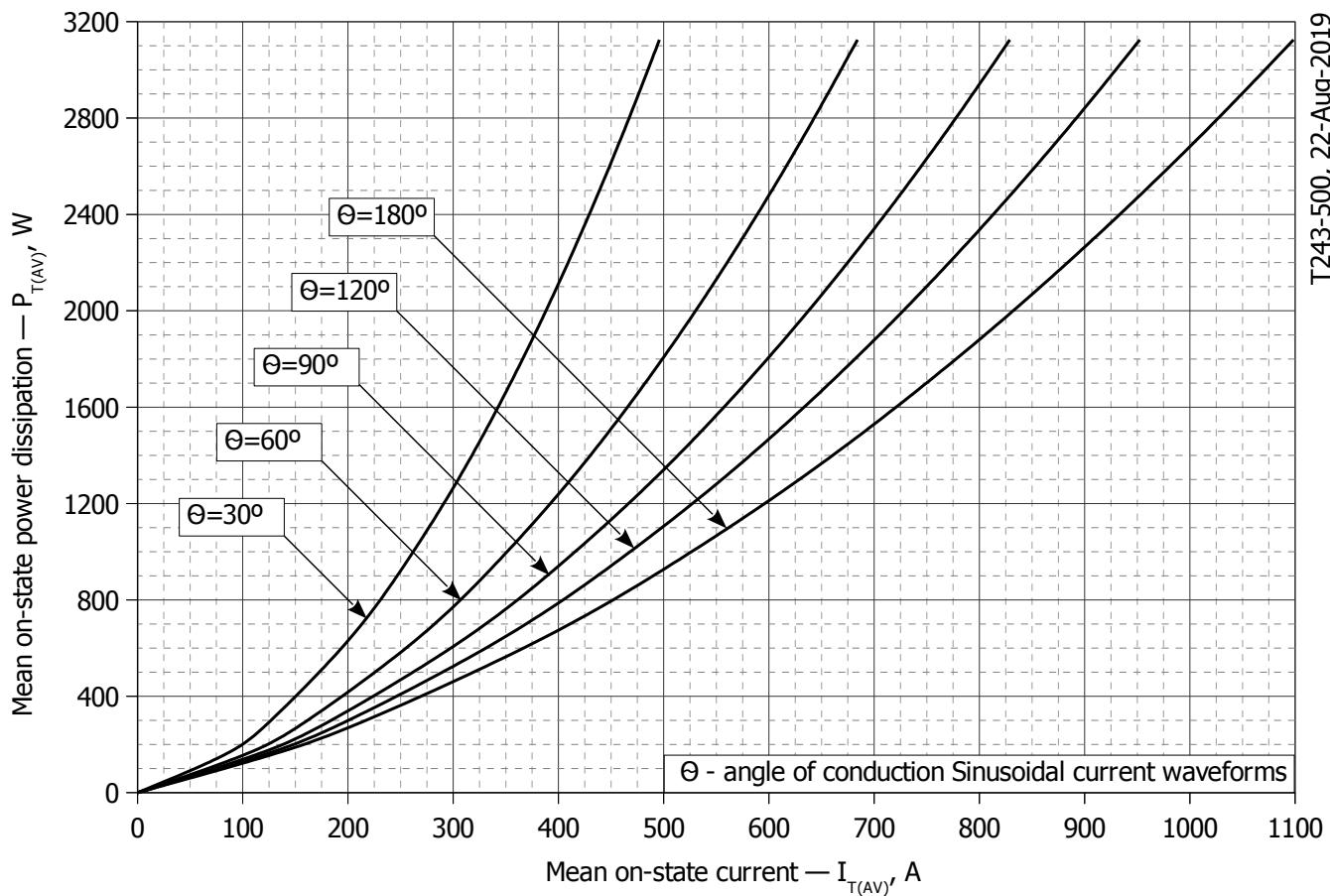


Fig. 7 - Mean on-state power dissipation P_{TAV} vs. mean on-state current I_{TAV} for sinusoidal current waveforms at different conduction angles (f=50Hz, DSC)

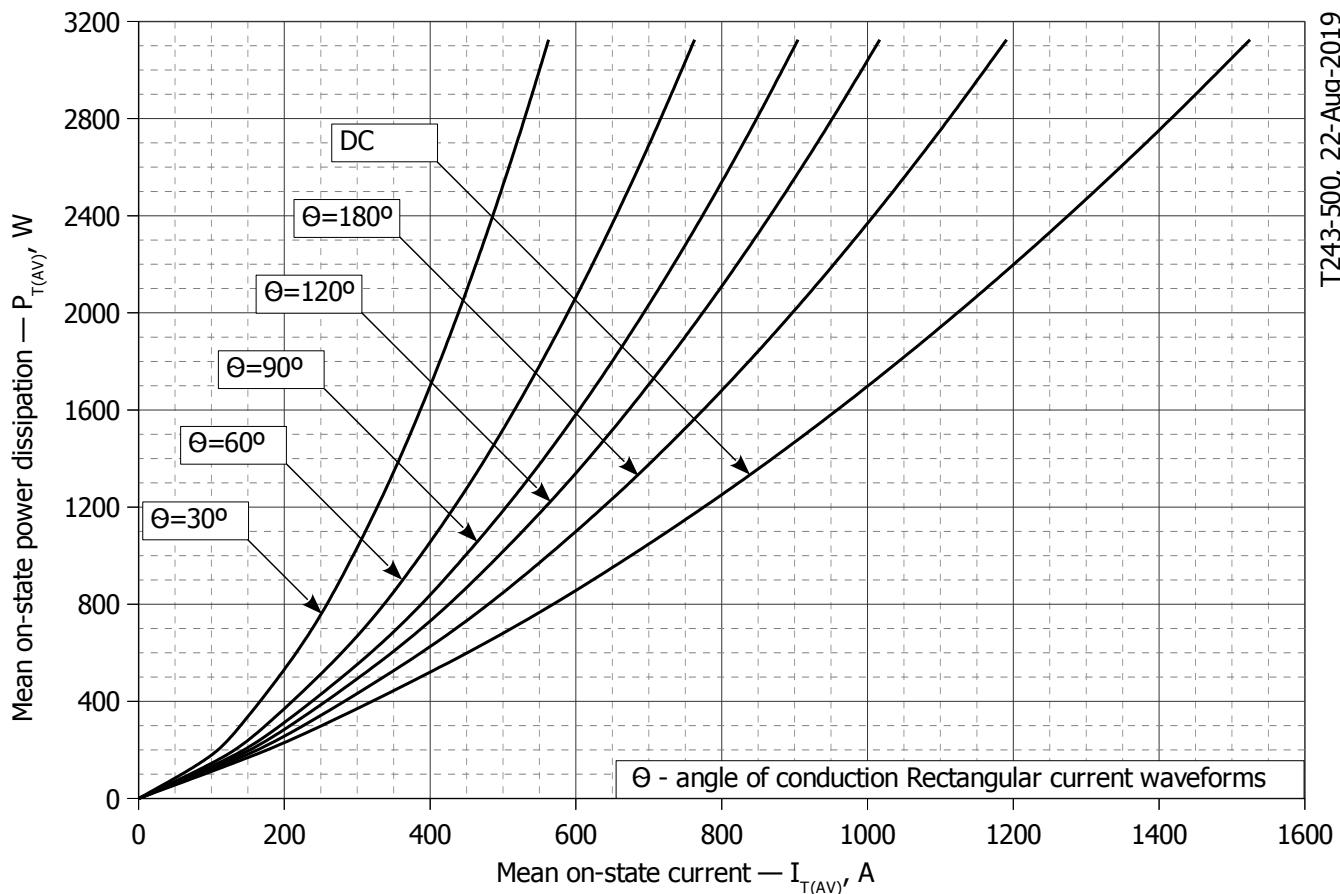


Fig. 8 – Mean on-state power dissipation P_{TAV} vs. mean on-state current I_{TAV} for rectangular current waveforms at different conduction angles and for DC (f=50Hz, DSC)

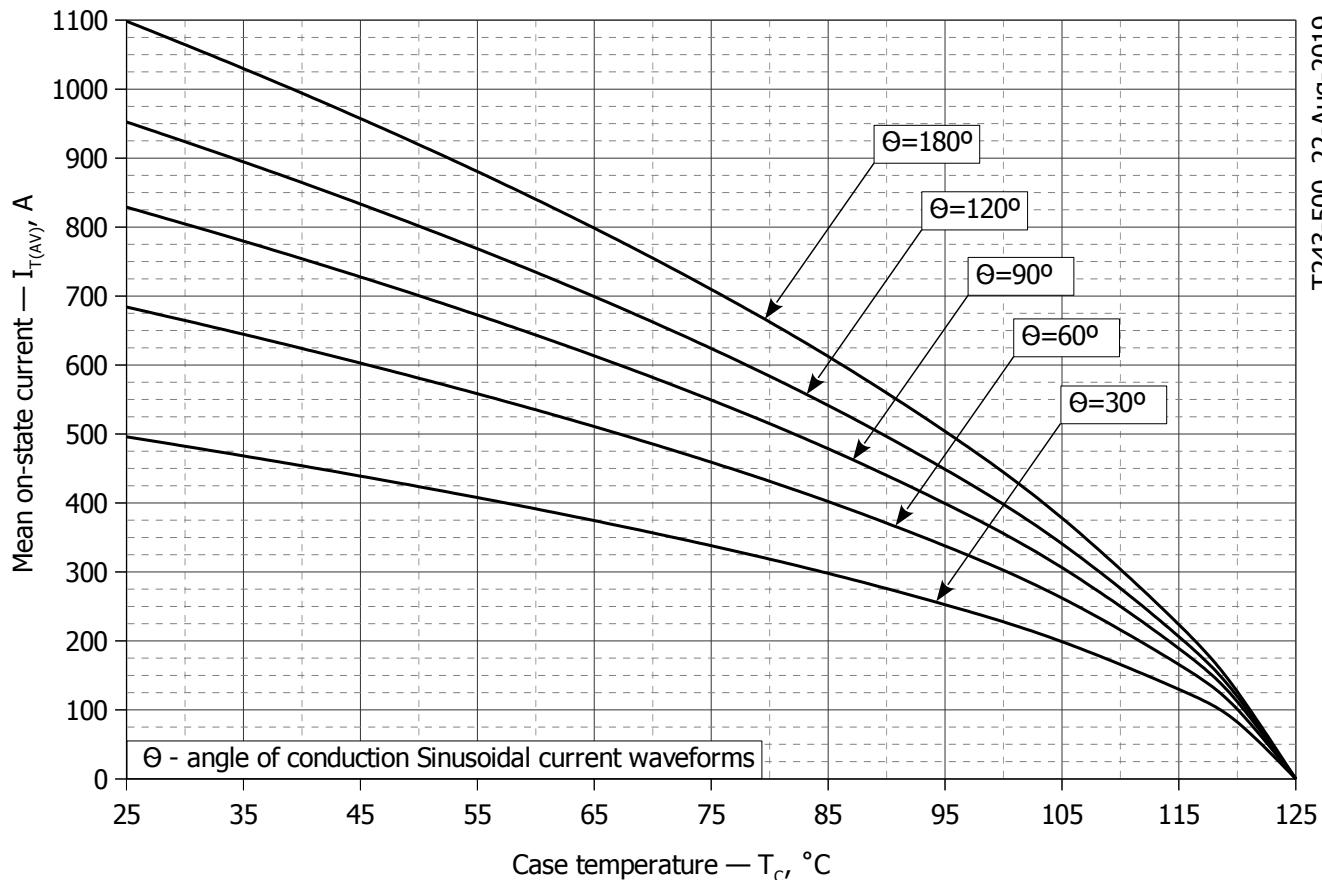


Fig. 9 – Mean on-state current I_{TAV} vs. case temperature T_c for sinusoidal current waveforms at different conduction angles (f=50Hz, DSC)

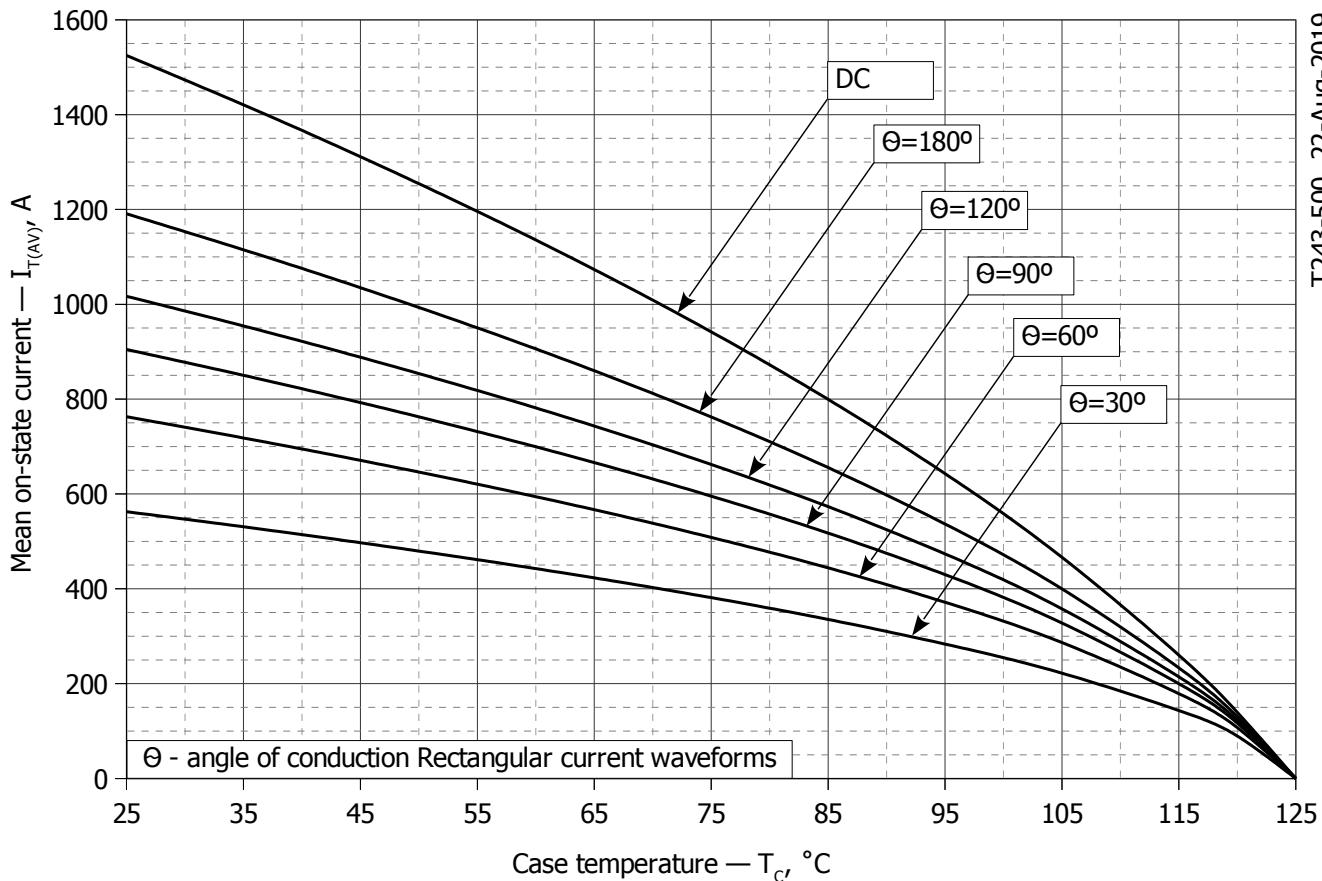


Fig. 10 - Mean on-state current I_{TAV} vs. case temperature T_c for rectangular current waveforms at different conduction angles and for DC (f=50Hz, DSC)

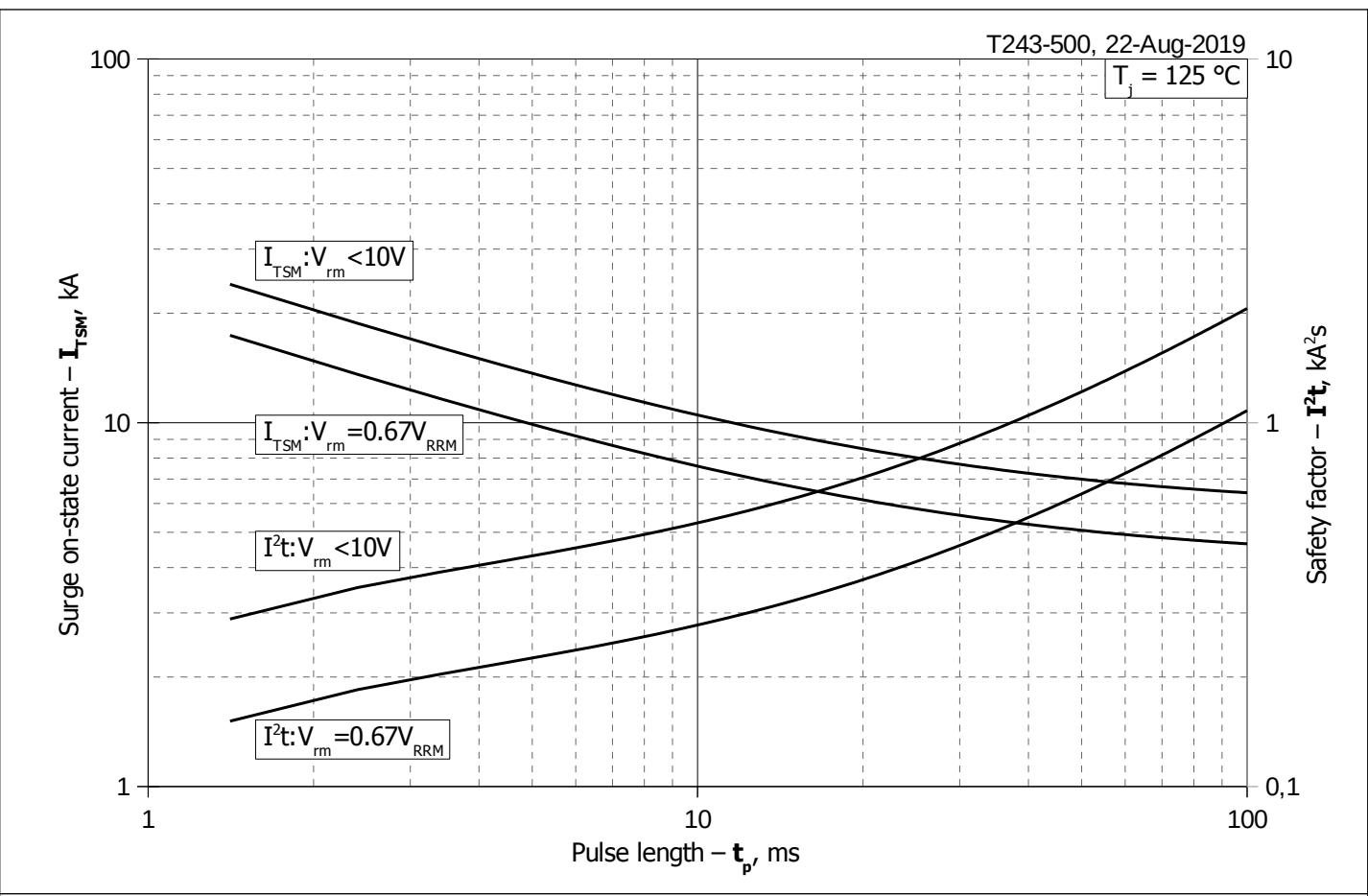


Fig. 11 – Maximum surge on-state current I_{TSM} and safety factor I^2t vs. pulse length t_p

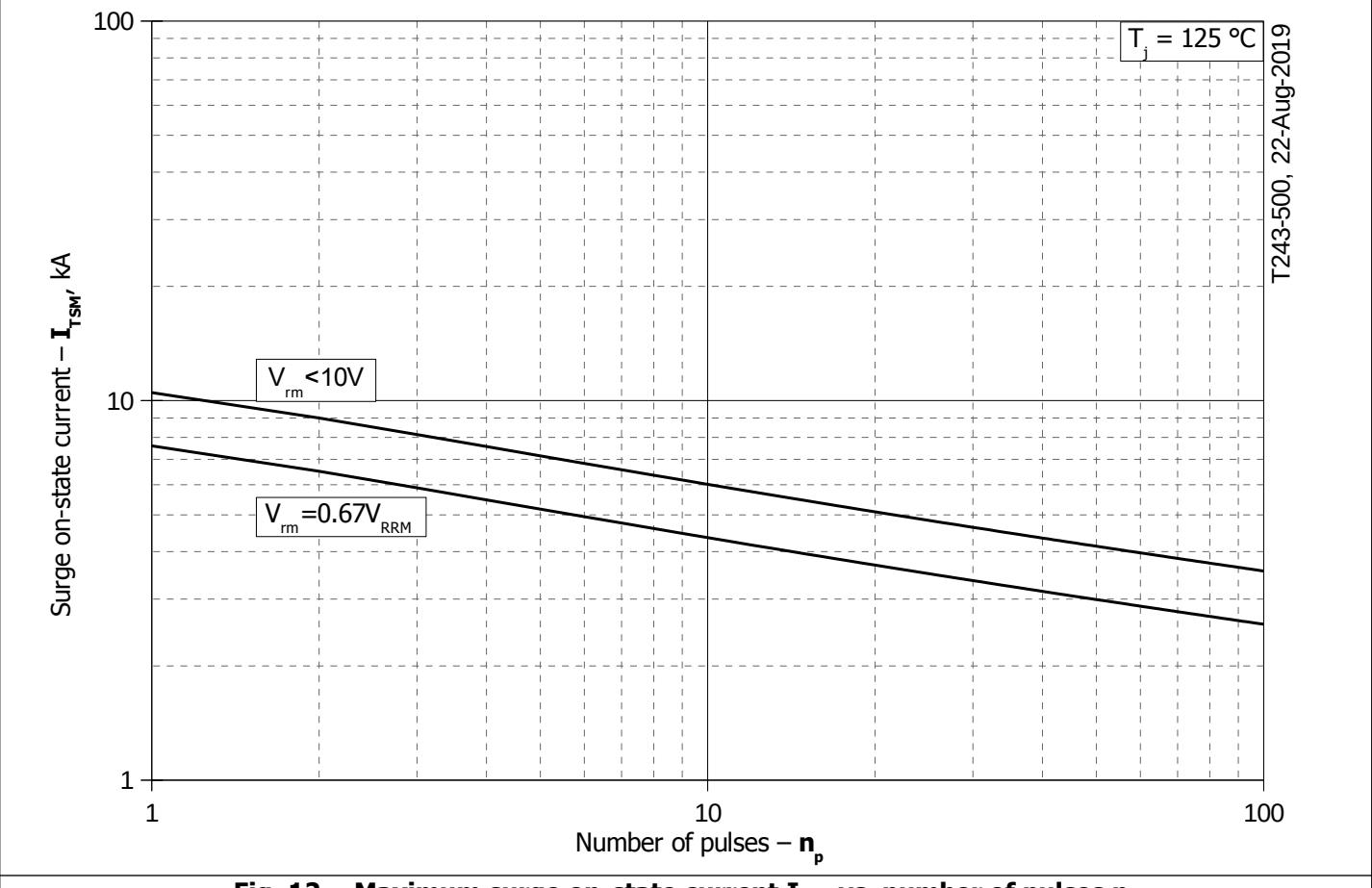


Fig. 12 - Maximum surge on-state current I_{TSM} vs. number of pulses n_p